



Phase Control Thyristors (Hockey PUK Version), 990 A



B-PUK (TO-200AC)

FEATURES

- Center amplifying gate
- Metal case with ceramic insulator
- International standard case B-PUK (TO-200AC)
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT

TYPICAL APPLICATIONS

- DC motor controls
- Controlled DC power supplies
- AC controllers

PRIMARY CHARACTERISTICS	
$I_{T(AV)}$	990 A
V_{DRM}/V_{RRM}	800 V, 1200 V, 1400 V, 1600 V, 1800 V, 2000 V
V_{TM}	1.62 V
I_{GT}	100 mA
T_J	-40 °C to +125 °C
Package	B-PUK (TO-200AC)
Circuit configuration	Single SCR

MAJOR RATINGS AND CHARACTERISTICS			
PARAMETER	TEST CONDITIONS	VALUES	UNITS
$I_{T(AV)}$		990	A
	T_{hs}	55	°C
$I_{T(RMS)}$		2000	A
	T_{hs}	25	°C
I_{TSM}	50 Hz	17 800	A
	60 Hz	18 700	
I^2t	50 Hz	1591	kA ² s
	60 Hz	1452	
V_{DRM}/V_{RRM}		800 to 2000	V
t_q	Typical	150	µs
T_J		-40 to 125	°C

VOLTAGE RATINGS				
TYPE NUMBER	VOLTAGE CODE	V_{DRM}/V_{RRM} , MAXIMUM REPETITIVE PEAK AND OFF-STATE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK VOLTAGE V	I_{DRM}/I_{RRM} MAXIMUM AT $T_J = T_J$ MAXIMUM mA
VS-ST730CL	08	800	900	80
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	
	18	1800	1900	
	20	2000	2100	



ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average on-state current at heatsink temperature	$I_{T(AV)}$	180° conduction, half sine wave double side (single side) cooled		990 (375)	A
				55 (85)	°C
Maximum RMS on-state current	$I_{T(RMS)}$	DC at 25 °C heatsink temperature double side cooled		2000	A
Maximum peak, one-cycle non-repetitive surge current	I_{TSM}	t = 10 ms	No voltage reapplied	17 800	
		t = 8.3 ms		18 700	
		t = 10 ms	100 % V_{RRM} reapplied	15 000	
		t = 8.3 ms		15 700	
Maximum I^2t for fusing	I^2t	t = 10 ms	No voltage reapplied	1591	kA ² s
		t = 8.3 ms		1452	
		t = 10 ms	100 % V_{RRM} reapplied	1125	
		t = 8.3 ms		1027	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reapplied		15 910	kA ² √s
Low level value of threshold voltage	$V_{T(TO)1}$	(16.7 % × π × $I_{T(AV)}$ < I < π × $I_{T(AV)}$), $T_J = T_J$ maximum		0.98	V
High level value of threshold voltage	$V_{T(TO)2}$	(I > π × $I_{T(AV)}$), $T_J = T_J$ maximum		1.12	
Low level value of on-state slope resistance	r_{t1}	(16.7 % × π × $I_{T(AV)}$ < I < π × $I_{T(AV)}$), $T_J = T_J$ maximum		0.32	mΩ
High level value of on-state slope resistance	r_{t2}	(I > π × $I_{T(AV)}$), $T_J = T_J$ maximum		0.27	
Maximum on-state voltage	V_{TM}	$I_{pk} = 2000$ A, $T_J = T_J$ maximum, $t_p = 10$ ms sine pulse		1.62	V
Maximum holding current	I_H	$T_J = 25$ °C, anode supply 12 V resistive load		600	mA
Typical latching current	I_L			1000	

SWITCHING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum non-repetitive rate of rise of turned-on current	di/dt	Gate drive 20 V, 20 Ω, $t_r \leq 1$ μs $T_J = T_J$ maximum, anode voltage ≤ 80 % V_{DRM}		1000	A/μs
Typical delay time	t_d	Gate current 1 A, $di_g/dt = 1$ A/μs $V_d = 0.67$ % V_{DRM} , $T_J = 25$ °C		1.0	μs
Typical turn-off time	t_q	$I_{TM} = 750$ A, $T_J = T_J$ maximum, $di/dt = 60$ A/μs, $V_R = 50$ V, $dV/dt = 20$ V/μs, gate 0 V 100 Ω, $t_p = 500$ μs		150	

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = T_J$ maximum linear to 80 % rated V_{DRM}		500	V/μs
Maximum peak reverse and off-state leakage current	I_{RRM} , I_{DRM}	$T_J = T_J$ maximum, rated V_{DRM}/V_{RRM} applied		80	mA



TRIGGERING						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES		UNITS	
			Typ.	Max.		
Maximum peak gate power	P_{GM}	$T_J = T_J$ maximum, $t_p \leq 5$ ms	10.0		W	
Maximum average gate power	$P_{G(AV)}$	$T_J = T_J$ maximum, $f = 50$ Hz, $d\% = 50$	2.0			
Maximum peak positive gate current	I_{GM}	$T_J = T_J$ maximum, $t_p \leq 5$ ms	3.0		A	
Maximum peak positive gate voltage	$+V_{GM}$	$T_J = T_J$ maximum, $t_p \leq 5$ ms	20		V	
Maximum peak negative gate voltage	$-V_{GM}$		5.0			
DC gate current required to trigger	I_{GT}	$T_J = -40$ °C	Maximum required gate trigger/ current/voltage are the lowest value which will trigger all units 12 V anode to cathode applied	200	-	mA
		$T_J = 25$ °C		100	200	
		$T_J = 125$ °C		50	-	
DC gate voltage required to trigger	V_{GT}	$T_J = -40$ °C		2.5	-	V
		$T_J = 25$ °C		1.8	3.0	
		$T_J = 125$ °C		1.1	-	
DC gate current not to trigger	I_{GD}	$T_J = T_J$ maximum	10		mA	
DC gate voltage not to trigger	V_{GD}		0.25		V	

THERMAL AND MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum operating junction temperature range	T_J		-40 to 125	°C
Maximum storage temperature range	T_{Stg}		-40 to 150	
Maximum thermal resistance, junction to heatsink	R_{thJ-hs}	DC operation single side cooled	0.073	K/W
		DC operation double side cooled	0.031	
Maximum thermal resistance, case to heatsink	R_{thC-hs}	DC operation single side cooled	0.011	
		DC operation double side cooled	0.006	
Mounting force, ± 10 %			14 700 (1500)	N (kg)
Approximate weight			255	g
Case style		See dimensions - link at the end of datasheet	B-PUK (TO-200AC)	

ΔR_{thJ-hs} CONDUCTION						
CONDUCTION ANGLE	SINUSOIDAL CONDUCTION		RECTANGULAR CONDUCTION		TEST CONDITIONS	UNITS
	SINGLE SIDE	DOUBLE SIDE	SINGLE SIDE	DOUBLE SIDE		
180°	0.009	0.009	0.006	0.006	$T_J = T_J$ maximum	K/W
120°	0.011	0.011	0.010	0.011		
90°	0.014	0.014	0.015	0.015		
60°	0.020	0.020	0.021	0.021		
30°	0.036	0.036	0.036	0.036		

Note

- The table above shows the increment of thermal resistance R_{thJ-hs} when devices operate at different conduction angles than DC



Fig. 1 - Current Ratings Characteristics



Fig. 4 - Current Ratings Characteristics



Fig. 2 - Current Ratings Characteristics



Fig. 5 - On-State Power Loss Characteristics



Fig. 3 - Current Ratings Characteristics



Fig. 6 - On-State Power Loss Characteristics

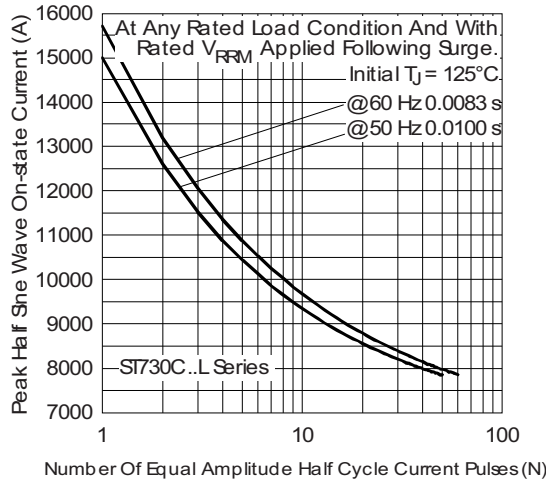


Fig. 7 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

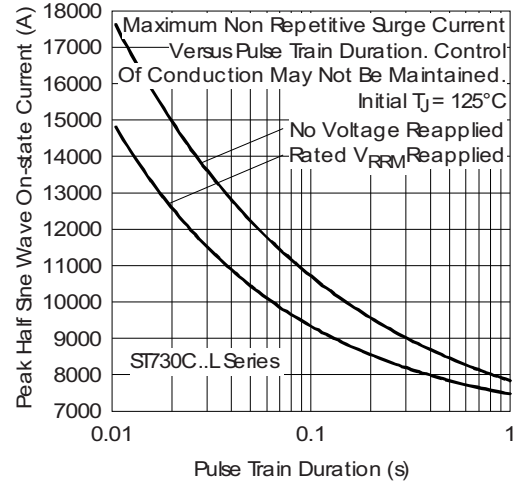


Fig. 8 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

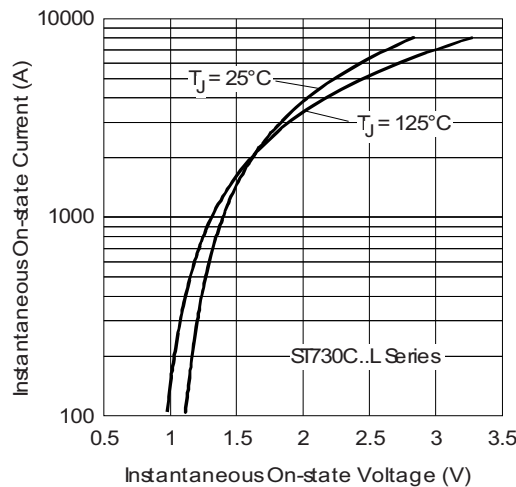


Fig. 9 - On-State Voltage Drop Characteristics

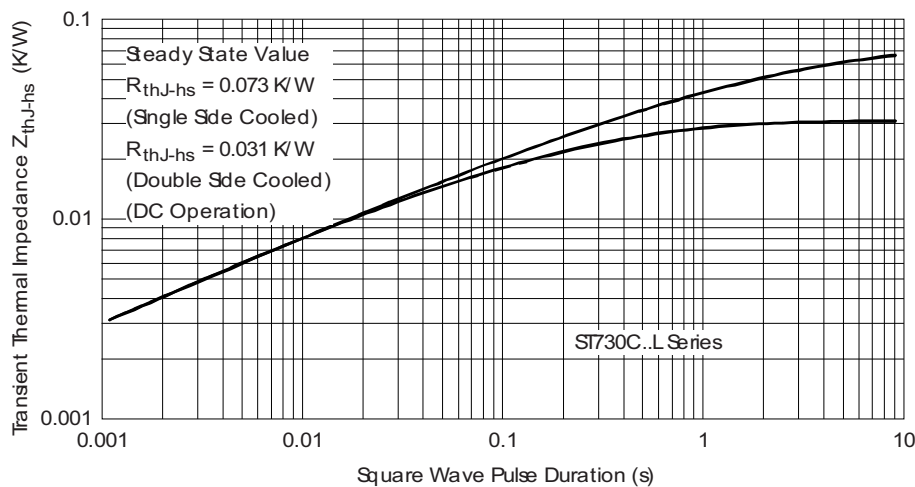


Fig. 10 - Thermal Impedance Z_{thj-hs} Characteristics



Fig. 11 - Gate Characteristics

ORDERING INFORMATION TABLE

Device code	VS-	ST	73	0	C	20	L	1	-
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1** - Vishay Semiconductors product
- 2** - Thyristor
- 3** - Essential part number
- 4** - 0 = converter grade
- 5** - C = ceramic PUK
- 6** - Voltage code x 100 = V_{RRM} (see Voltage Ratings table)
- 7** - L = PUK case B-PUK (TO-200AC)
- 8** - 0 = eyelet terminals (gate and auxiliary cathode unsoldered leads)
 1 = fast-on terminals (gate and auxiliary cathode unsoldered leads)
 2 = eyelet terminals (gate and auxiliary cathode soldered leads)
 3 = fast-on terminals (gate and auxiliary cathode soldered leads)
- 9** - Critical dV/dt: • None = 500 V/μs (standard selection)
 • L = 1000 V/μs (special selection)

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95076



B-PUK (TO-200AC)

DIMENSIONS in millimeters (inches)

Creepage distance: 36.33 (1.430) minimum
Strike distance: 17.43 (0.686) minimum



Note:
A = Anode
C = Cathode



Quote between upper and lower pole pieces has to be considered after application of mounting force (see thermal and mechanical specification)



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